isola

370HR

Industry Leading Epoxy Laminate and Prepreg Tg 180°C Td 340°C Dk 4.04 Df 0.021

IPC-4101 /98 /99 /101 /126 UL - File E41625 Grade PCL-FR-370HR

TEST again. 370HR is the industry's "best in class" leadfree compatible product for high-reliability applications across a wide range of markets.

PRODUCT FEATURES

Industry Recognition

- UL File Number: E41625
- Polyclad[®]Grade PCL-FR-370HR
- Qualified to UL's MCIL Program
- RoHS Compliant

Performance Attributes

CAF resistant

Processing Advantages

- FR-4 process compatible
- UV blocking and AOI fluorescence
- Multiple reflow capable
- HDI technology compatible

PRODUCT AVAILABILITY

Standard Material Offering: Laminate

• 2 to 125 mil (0.05 to 3.2 mm)

Copper Foil Type

• HTE Grade 3

- RTF (Reverse Treat Foil)
- Embedded resistor foil

Copper Weight

- $\frac{1}{2}$, 1 and 2 oz (18, 35 and 70 μ m) available
- Heavier copper foil available
- Thinner copper foil available
- Standard Material Offering: Prepreg
- Tooling of prepreg panels
- Glass Fabric Availability
 - E-glass
 - Square weave glass
 - Mechanically spread glass

ORDERING INFORMATION:

Contact your local sales representative or contact info@isola-group.com for further information.

370HR laminates and prepregs, designed by Polyclad, are made using a patented high performance 180°C Tg FR-4 multifunctional epoxy resin system that is designed for multilayer Printed Wiring Board (PWB) applications where maximum thermal performance and reliability are required. We manufacture 370HR laminates and prepregs with high quality E-glass glass fabric for superior Conductive Anodic Filament (CAF) resistance. 370HR provides superior thermal performance with low Coefficient of Thermal Expansion (CTE) and the mechanical, chemical and moisture resistance properties that equal or exceed the performance of traditional FR-4 materials.

370HR is used in thousands of PWB designs and has proven to be best in class for thermal reliability, CAF performance, ease of processing and proven performance on sequential lamination designs.

PRODUCT ATTRIBUTES





TYPICAL MARKET APPLICATIONS



AEROSPACE & DEFENSE

COMPUTING, STORAGE

ELECTRONICS

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Typical Values Table

			Units	Test Method
Property		Typical Value	Metric (English)	IPC-TM-650 (or as noted)
Glass Transition Temperature (Tg) by DSC		180	°C	2.4.25C
Decomposition Temperature (Td) by TGA @ 5% weight loss		340	°C	2.4.24.6
Time to Delaminate by TMA	A. T260	60	Minutes	2.4.24.1
(Copper removed)	В. Т288	30	Minuces	2.7.27.1
Z-Axis CTE	A. Pre-Tg	45	ppm/°C ppm/°C	2.4.24C
	B. Post-Tg	230		
	C. 50 to 260°C, (Total Expansion)	2.8	%	
X/Y-Axis CTE	Pre-Tg	13/14	ppm/°C	2.4.24C
Thermal Conductivity		0.4	W/m·K	ASTM E1952
Thermal Stress 10 sec @	A. Unetched	Pass	Pass Visual	2.4.13.1
288ºC (550.4ºF)	B. Etched			
Dk, Permittivity	A. @ 100 MHz	4.24	_	2.5.5.3
	B. @ 1 GHz	4.17		2.5.5.9
	C. @ 2 GHz	4.04		Bereskin Stripline
	D. @ 5 GHz	3.92		Bereskin Stripline
	E. @ 10 GHz	3.92		Bereskin Stripline
Df, Loss Tangent	A. @ 100 MHz	0.0150		2.5.5.3
	B. @ 1 GHz	0.0161	-	2.5.5.9
	C. @ 2 GHz	0.0210	-	Bereskin Stripline
	D. @ 5 GHz	0.0250	-	2.5.5.5
	E. @ 10 GHz	0.0250		2.5.5.5
Volume Resistivity	A. After moisture resistance	3.0 x 10 ⁸	MΩ-cm	2.5.17.1
	B. At elevated temperature	7.0 x 10 ⁸		
Surface Resistivity	A. After moisture resistance	3.0×10^{6}	ΜΩ	2.5.17.1
-	B. At elevated temperature	2.0 x 10 ⁸		
Dielectric Breakdown		>50	kV	2.5.6B
Arc Resistance		115	Seconds	2.5.1B
Electric Strength (Laminate & laminated prepreg)		54 (1350)	kV/mm (V/mil)	2.5.6.2A
Comparative Tracking Index (CTI)		3 (175-249)	Class (Volts)	UL 746A ASTM D3638
Peel Strength	A. Low profile copper foil and very low profile		N/mm (lb/inch)	2.4.8C
	copper foil all copper foil >17 μ m [0.669 mil]	1.14 (6.5)		2.4.00
	B. Standard profile copper	1.25 (7.0)		2.4.8.2A
	1. After thermal stress	1.25 (7.0)		2.4.8.3
	2. At 125°C (257°F)	1.14 (6.5)		2.4.8.3
	3. After process solutions			
Flexural Strength	A. Length direction	6201 (90.0)	MPa (kpsi)	2.4.4B
-	B. Cross direction	531 (77.0)	,	
Tensile Strength	A. Length direction	385 (55.9)	MPa (kpsi)	ASTM D3039
	B. Cross direction	245 (35.6)		
Young's Modulus	A. Length direction	3744	ksi	ASTM D790-15e2
	B. Cross direction	3178		
Poisson's Ratio	A. Length direction	0.177		
	B. Cross direction	0.171	-	ASTM D3039
Moisture Absorption		0.15	%	2.6.2.1A
Flammability (Laminate & laminated prepreg)		V-0	Rating	UL 94
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NOTES

Visit our site <u>http://www.isola-group.com</u> for more details. Revisions:

- A: Initial release 4/17
- B: Corrected units for Flexural and Tensile Strength 8/18
- C: Change MOT to RTI 5/19
- D: Changed VLP2 to HVLP to align with common industry terms 4/21

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